



Benefits

• Reduce time to market

- Intrinsic BSP Kits provide you with critical features early in your development cycle allowing you to jumpstart your system and application integration
- Intrinsic BSP Reports identify potential product integration issues early in the product development cycle allowing you to address critical issues sooner

• Reduce costs

- Focus your development efforts and reduce costs with our Intrinsic selectable driver sets
- Identify potential costly hardware issues early with Intrinsic BSP Reports

• Reduce risks

- Work with an established Windows CE BSP expert: Intrinsic has implemented BSPs on leading embedded processors including Intel® XScale®, Texas Instruments OMAP and Samsung ARM based processors
- Leverage expertise: Intrinsic was the first company to deliver a Windows CE BSP for an Intel® StrongArm based single board computer
- Work with a credible industry expert: Intrinsic is a founding member of Microsoft's Mobile Partner Advisory Council and a Gold Member of the Windows Embedded Partner (WEP) program

Windows CE BSP Kits

Overview

Intrinsic Software offers a series of kits for each integral step of your BSP development cycle (see figure 1). Intrinsic's Windows CE BSP Kits help you reduce your time to market, development costs and project risks. By partnering with an established and experienced Windows CE BSP expert, you can develop and launch your products faster and more cost effectively.

Intrinsic's engineers are experts at implementing Windows CE BSPs on a wide range of embedded processors from key silicon vendors including Intel® XScale®, Texas Instruments OMAP and Samsung ARM based processors. As a recognized Microsoft partner and an extensive BSP provider, you can be confident in our ability to provide you with the BSPs and the processor platform knowledge and understanding you need to accelerate your project.

Intrinsic offers Windows CE BSP Kits at fixed prices, allowing you to plan your next product with certainty and confidence. Additional BSP catalogue components and drivers are available for your specific implementation.

Figure 1: How Intrinsic's Service Kits can enhance your BSP development cycle



Features

Intrinsic leverages years of expertise, an extensive library of OEM Adaptation Layer code, and a catalogue of components and drivers to provide you with a Windows CE BSP kit that matches the specific needs of your platform.

Processor Specific Base BSPs

Intrinsic builds your BSP from a strong initial foundation. Intrinsic starts with a processor specific base BSP that delivers the core components required for that processor as well as the components common to all Windows CE BSP implementations.

Multiple BSP Releases

Key issues with product features, functionality and hardware are identified early to jumpstart your system and application integration. Multiple BSP releases are provided during the implementation of your BSP. Core, Preliminary, and Feature Complete releases give you the critically timed features and functionality when and as you need it during your product development cycle.

Locations

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All specifications are subject to change without notice.

BSP Release Reports

Each BSP release includes a BSP Release Report detailing the components, drivers and their current functional state along with any platform issues discovered at this BSP stage. Intrinsyc's BSP Release Reports enable you to address potential costly issues early in the product development cycle, saving you time and money.

Product Specifications

Intrinsyc offers you the ability to choose additional drivers from the Windows CE BSP Driver catalogue for the Preliminary and Feature Complete BSP releases.

Hardware Bring-up

Core BSP

- The Core BSP provides memory configuration, boot media driver, basic OAL support RAM/Flash verification. A preliminary implementation of a key driver, such as a display driver, can also be included in this release.

Bring-up Report

- The Bring-up report provides you with an in-depth report and system configuration, memory configuration, hardware configuration, initial performance assessment and an issues list.

Preliminary BSP

Intrinsyc's Windows CE Preliminary BSP includes rudimentary versions of all the drivers you require for starting application development on your platform.

Build Environment

- Intrinsyc provides a build environment including makefiles with build configuration information (include and library file paths).

Bootloader

- The bootloader places the run-time image (of the OS) into memory, and jumps to the OS startup routine.

Kernel & OAL

- Enable CPU core, including the SDRAM controller, memory management unit (MMU), and caches.
- Configure the GPIO, memory controller, interrupt controller and initialize the real time clock and turn on board-level and peripheral clocks, perform memory and peripheral initializations, busses required to boot kernel only.
- Initialize the debug subsystem and OAL time functions. Enable Kernel Independent Transport Layer (KITL) support and any Windows CE required media drivers.

Feature Complete BSP

Intrinsyc's Windows CE Feature Complete BSP includes feature complete versions of all the drivers you require. This release of the BSP is ready for BSP Optimization and formal testing (CETK).

